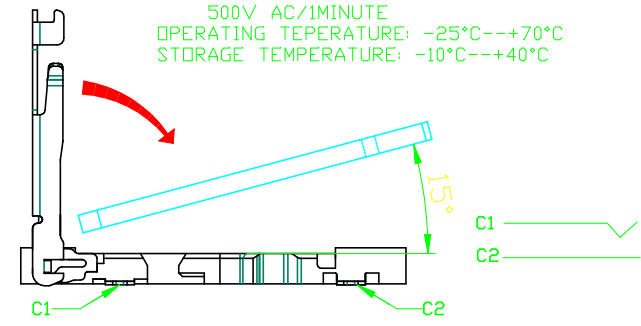
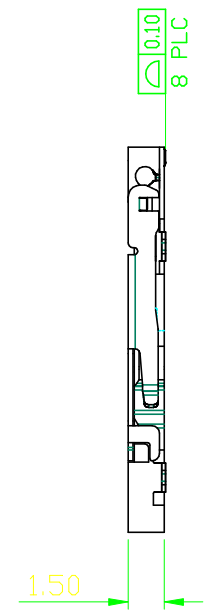
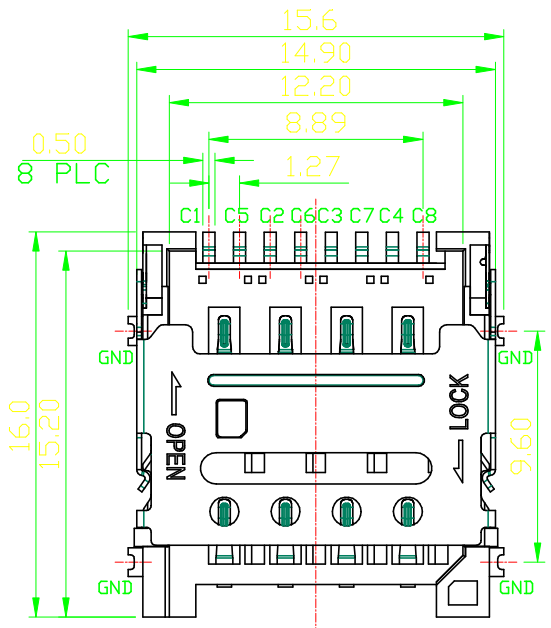
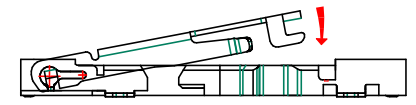


REV.	ECN.ND.	MODIFY.CONTENT	DATE
A		NEW	2016/08/08

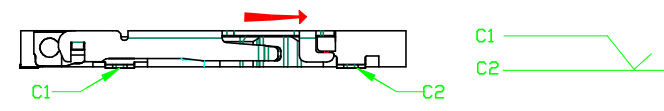
NOTES:
 1)MATERIAL:
 HOUSING: LCP E130i UL 94V-0
 CONTACT: C5210R-H T=0.15mm
 SHELL: SUS201-H T=0.20mm
 2)FINISH :
 CONTACT:GOLD FLASH PLATED ON CONTACT AREA 1u*Min ;
 GOLD FLASH PLATING ON SOLDER TAILS 1u*Min,
 WITH ENTIRE CONTACT UNDERPLATED NICKEL 50u*Min
 SHELL: NICKEL UNDERPLATED OVERALL 50u*Min,
 3)MECHANICAL CHARACTERISTICS
 CONTACT RETENTION: 50gf/pin Min
 MATING CYCLE:3000 CYCLES
 4)ELECTRICAL CHARACTERISTICS
 RATING CURRENT: 1A
 RATING VOLTAGE: 30V
 CONTACT RESISTANCE: 30 MILLOHMS OHMS MAX
 INSULATION RESISTANCE:
 a, UNMATED: 1000M OHMS MIN
 b, MATED: 100M OHMS MIN
 DIELECTRIC WITHSTANDING VOLTAGE:
 500V AC/1MINUTE
 OPERATING TEMPERATURE: -25°C--+70°C
 STORAGE TEMPERATURE: -10°C--+40°C



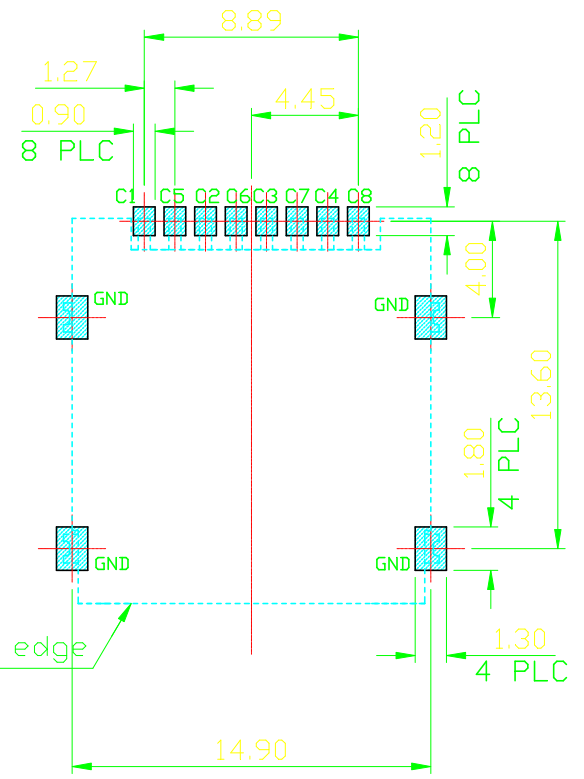
STEP I INSERT MICRO SIM CARD (C1/C2 SWITCH OPEN)



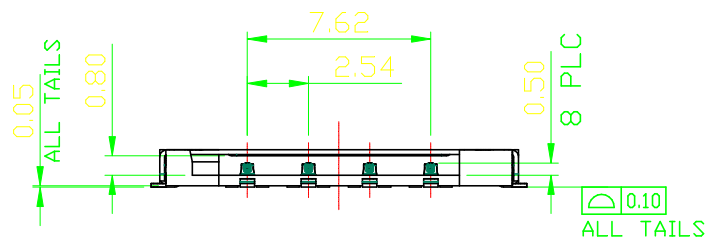
STEP II



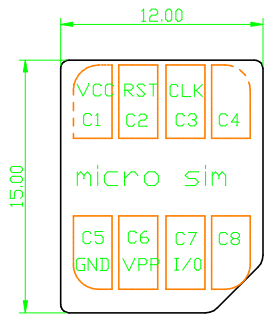
STEP III PUSH SHELL (C1/C2 SWITCH LOCK)



RECOMMENDED PCB LAYOUT(TOP VIEW)
 GENERAL TOLERANCES:±0.05



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



芯片面朝下视图

GENERAL TOLERANCE		DWG NO.	A1505-001	APPD:	WIND	Scale	1:1
X±0.45	x.*±5°	Title	MICRO SIM CARD 8PIN	CHKD:		UNIT	mm
.X±0.35	.x.*±2°		1.5H (掀盖式8X1PIN)	DR:			
.XX±0.25	.xx.*±1°	Part NO.	SIM150-071	Date	2016/03/15		
.XXX±0.15	.xxx.*±0.5°						
SHEET	1/1						